

DOCKET No.: 122302.00001

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Oliver Chyan, et al.

Serial No.: 10/600,039

Filed: June 20, 2003

Art Unit: 2818

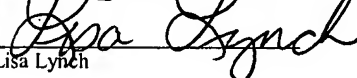
Examiner: Mai Huong C. Tran

For: **METHOD OF USING MATERIALS BASED ON RUTHENIUM AND  
IRIDIUM AND THEIR OXIDES, AS A CU DIFFUSION BARRIER, AND  
INTEGRATED CIRCUITS INCORPORATING THE SAME**

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on December 3, 2004.

  
Lisa Lynch

**RESPONSE TO RESTRICTION REQUIREMENT**

In response to the Office Action mailed November 12, 2004, Applicant hereby elects, without traverse, to prosecute in this application Set of Claims 1-10, Set of Claims 25-29, Set of Claims 31-32 and Set of Claims 33-34, comprising Species I, drawn to a method of controlling copper diffusion using a layer of RuO<sub>2</sub> as a diffusion stuffer having a layer of Ru on the inter-level dielectric substrate.

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Respectfully submitted,



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December 3, 2004

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Date